

## AMENDMENTS

### In the Specification

Please amend the paragraphs beginning on page 3, line 10 as follows:

Fig. 1 is a schematic diagram illustrating the system architecture of the system for equipment malfunction detection and diagnosis according to the embodiment of the present invention; [[and]]

Fig. 2 is a flowchart showing the process for the method for equipment malfunction detection and diagnosis according to the embodiment of the present invention; and

Fig. 3 is a schematic diagram illustrating semiconductor furnace equipment and status information therein.

Please amend the paragraph beginning on page 3, line 26 as follows:

The equipment 10 may be semiconductor furnace equipment, but is not limited thereto.

The equipment 10 transfers status information of the equipment 10 to the detection/diagnosis unit 11 at preset intervals, such as 15 seconds. It is understood that the status information of the equipment 10 may include a parameter value corresponding to at least one process parameter, in which Fig. 3 is a schematic diagram illustrating semiconductor furnace equipment and status information therein. As shown in Fig. 3, the status information 310 of the semiconductor furnace equipment 300 comprises the parameter value for the process parameters may be comprising a processed material ID (identity) 311, a wafer count 312, a process program ID 313, a chamber ID 314, an operator ID 315, a boat map 316, a step ID 317, a zone temperature 318, a pressure 319, a MFC (Mass Flow Controller) 320, a gas flow 321, a valve opening angle 322 or a leakage

pressure 323. It is understood that the process parameter may differ for various equipment and processes, and thus is not limited to the above-described examples.